

DOW CORNING® 732 Multi-Purpose Sealant

FEATURES

- One-component adhesive/sealant
- Cures at room temperature when exposed to moisture in the air
- Acetoxy cure system
- Non-sag, paste consistency
- Easy to apply
- Cures to a tough, flexible rubber
- Good adhesion to many substrates
- Stable and flexible from -60°C (-76°F) to +180°C (356°F), with short peaks up to +205°C (401°F)
- Black version: stable and flexible from -60°C (-76°F) to +205°C (401°F), with short peaks up to +230°C (446°F)
- Excellent dielectric properties
- Complies with MIL-A-46106
- Complies with FDA 177.2600
- Available in white, black or clear

General purpose silicone adhesive/sealant (specified)

APPLICATIONS

- General industrial sealing and bonding applications.
- Complies with MIL-A-46106 and FDA 177.2600.

TYPICAL PROPERTIES

Specification Writers: These values are not intended for use in preparing specifications. Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

CTM*	ASTM*	Property	Unit	Value
As supplied				
0176		Appearance		Non-slump paste
		Color(s)		White, black or clear
0364		Extrusion rate ¹	g/minute	350
0098		Skin-over time	minutes	7
0095		Tack-free time	minutes	20
Mechanical properties, cured 7 days in air at 25°C (77°F) and 50% relative humidity				
0097B	D1475	Specific gravity		1.04
0099	D2240	Durometer hardness, Shore A		25
0137A	D412	Tensile strength	MPa	2.3
0137A	D412	Elongation at break	%	540
0420		Volume coefficient of thermal expansion	1/K	1.12x10 ⁻³
Electrical properties, cured 7 days in air at 25°C (77°F) and 50% relative humidity				
0114	D149	Dielectric strength	kV/mm	21.6
0112	D150	Dielectric constant at 100Hz/100kHz		2.8
0112	D150	Dissipation factor at 100Hz/100kHz		0.0015
0112	D150	Volume resistivity	Ohm.cm	1.5x10 ¹⁵

1. Extrusion rate: 3.2mm orifice at 0.62MPa.

* CTM: Corporate Test Method, copies of CTMs are available on request.

ASTM: American Society for Testing and Materials.

HOW TO USE

Substrate preparation

All surfaces must be clean and dry. Degrease and wash off any contaminants that could impair adhesion. Suitable solvents include isopropyl alcohol, acetone or methyl ethyl ketone.

Unprimed adhesion may be obtained on many substrates such as glass, metals and most common engineering plastics. Substrates to which good adhesion is normally not obtained include PTFE, polyethylene, polypropylene and related materials.

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